



Material Content Data Sheet



Sales Product Name		BSZ028N04LS		Issued		25. January 2018		
MA#		MA001075720						
Package		PG-TSDSON-8-26		Weight*		36.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.552	1.51	1.51	15065	15065
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5367	
wire	non noble metal	copper	7440-50-8	7.988	21.79	22.37	217932	223634
	noble metal	gold	7440-57-5	0.028	0.08	0.08	770	770
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1010	
	plastics	epoxy resin	-	1.906	5.20		51999	
	inorganic material	silicondioxide	60676-86-0	16.562	45.17	50.47	451837	504846
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10783	10783
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	554	554
solder	noble metal	silver	7440-22-4	0.021	0.06		560	
	non noble metal	tin	7440-31-5	0.016	0.04		448	
	non noble metal	lead	7439-92-1	0.784	2.14	2.24	21386	22394
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2564	
	non noble metal	copper	7440-50-8	3.816	10.41	10.68	104103	106827
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2763	
	non noble metal	copper	7440-50-8	4.112	11.22	11.51	112191	115127
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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